





#### **COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET**

#### **Features**

- Low On-Resistance
- Low Gate Threshold Voltage V<sub>GS(th)</sub> <1V</li>
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Complementary Pair MOSFET
- Ultra-Small Surface Mount Package
- Lead Free/RoHS Compliant (Note 2)
- ESD Protected Gate to 2.5kV HBM
- "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

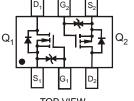
- Case: SOT-563
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin annealed over Copper leadframe.
   Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 7
- Ordering Information: See Page 7
- Weight: 0.006 grams (approximate)

SOT-563









TOP VIEW

BOTTOM VIEW

Internal Schematic

#### Maximum Ratings N-CHANNEL − Q<sub>1</sub> @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Drain Source Voltage	$V_{DSS}$	20	V
Gate-Source Voltage	$V_{GSS}$	±6	V
Drain Current (Note 1) $ T_A = 25^{\circ}C $ $ T_A = 85^{\circ}C $	l <sub>D</sub>	870 630	mA

## Maximum Ratings P-CHANNEL − Q<sub>2</sub> @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Drain Source Voltage	$V_{DSS}$	-20	V
Gate-Source Voltage	$V_{GSS}$	±6	V
Drain Current (Note 1) $ T_A = 25^{\circ}C $ $ T_A = 85^{\circ}C $	I <sub>D</sub>	-640 -460	mA

# **Thermal Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit	
Power Dissipation (Note 1)	$P_{D}$	530	mW	
Thermal Resistance, Junction to Ambient (Note 1)	$R_{ hetaJA}$	235	°C/W	
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C	

Notes:

- 1. Device mounted on FR-4 PCB.
- 2. No purposefully added lead.
- Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead\_free/index.php.



## Electrical Characteristics N-CHANNEL – Q<sub>1</sub> @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition		
OFF CHARACTERISTICS (Note 4)								
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	20	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>		_	100	nA	$V_{DS} = 20V, V_{GS} = 0V$		
Gate-Source Leakage	I <sub>GSS</sub>		_	± 1.0	μΑ	$V_{GS} = \pm 4.5V, V_{DS} = 0V$		
ON CHARACTERISTICS (Note 4)				_				
Gate Threshold Voltage	V <sub>GS(th)</sub>	0.5		1.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		
		_	0.3	0.4		$V_{GS} = 4.5V, I_D = 600mA$		
Static Drain-Source On-Resistance	R <sub>DS</sub> (ON)	_	0.4	0.5	Ω	$V_{GS} = 2.5V, I_D = 500mA$		
		_	0.5	0.7		$V_{GS} = 1.8V, I_D = 350mA$		
Forward Transfer Admittance	Y <sub>fs</sub>	_	1.4	_	S	$V_{DS} = 10V, I_D = 400 \text{mA}$		
Diode Forward Voltage (Note 4)		_	0.7	1.2	V	$V_{GS} = 0V, I_{S} = 150mA$		
DYNAMIC CHARACTERISTICS				_				
Input Capacitance	Ciss		60.67	_	pF			
Output Capacitance	Coss		9.68	_	pF	$V_{DS} = 16V, V_{GS} = 0V$ -f = 1.0MHz		
Reverse Transfer Capacitance	C <sub>rss</sub>		5.37	_	pF	1 = 1.0IVII IZ		
Total Gate Charge	Qg	_	736.6	_		\\\ 45\\\\\ 40\\\		
Gate-Source Charge	Q <sub>qs</sub>	_	93.6	_	рC	$V_{GS} = 4.5V, V_{DS} = 10V,$		
Gate-Drain Charge	Q <sub>gd</sub>	_	116.6	_		$I_D = 250 \text{mA}$		
Turn-On Delay Time	t <sub>d(on)</sub>	_	5.1	_		10)/ )/ 45)/		
Turn-On Rise Time	t <sub>r</sub>	_	7.4	_		$V_{DD} = 10V, V_{GS} = 4.5V,$		
Turn-Off Delay Time	t <sub>d(off)</sub>	_	26.7	_	ns	$R_L = 47\Omega$ , $R_G = 10\Omega$ , $I_D = 200$ mA		
Turn-Off Fall Time	t <sub>f</sub>	_	12.3	_		ID = ZUUIIA		

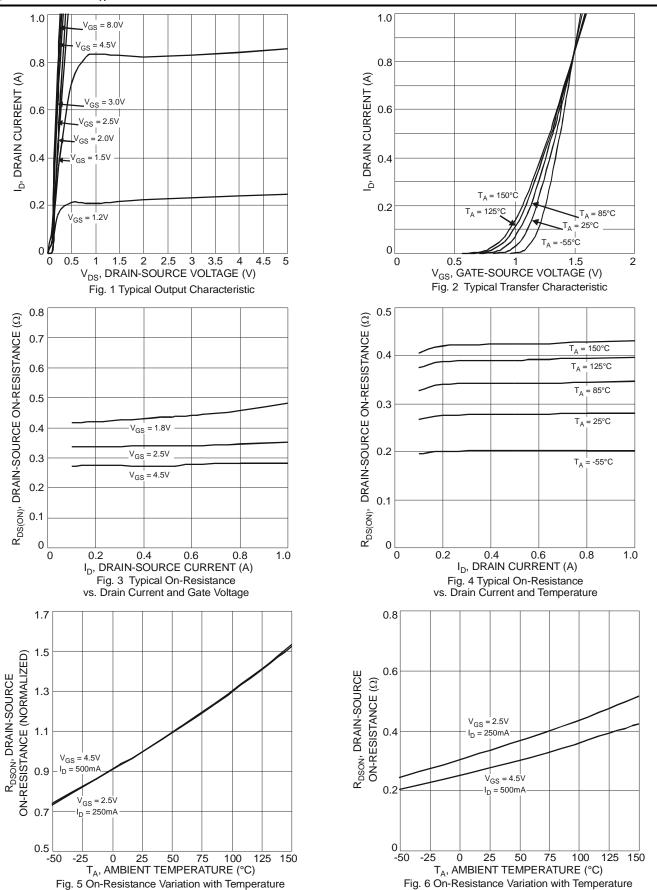
## Electrical Characteristics P-CHANNEL - Q<sub>2</sub> @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 4)			<b>/</b>				
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-20	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>		_	-100	nA	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	± 2.0	μΑ	$V_{GS} = \pm 4.5V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 4)							
Gate Threshold Voltage	V <sub>GS(th)</sub>	-0.5	_	-1.0	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
Static Drain-Source On-Resistance	R <sub>DS (ON)</sub>	_	0.5 0.7 1.0	0.7 0.9 1.3	Ω	$V_{GS} = -4.5V$ , $I_D = -430$ mA $V_{GS} = -2.5V$ , $I_D = -300$ mA $V_{GS} = -1.8V$ , $I_D = -150$ mA	
Forward Transfer Admittance	Y <sub>fs</sub>	_	-0.9	_	S	$V_{DS} = 10V, I_D = -250mA$	
Diode Forward Voltage (Note 4)		_	-0.8	-1.2	V	$V_{GS} = 0V, I_{S} = -150mA$	
DYNAMIC CHARACTERISTICS			_	_	_		
Input Capacitance	C <sub>iss</sub>		59.76	_	pF	101/11/	
Output Capacitance	Coss		12.07	_	pF	$V_{DS} = -16V, V_{GS} = 0V$ -f = 1.0MHz	
Reverse Transfer Capacitance	$C_{rss}$	_	6.36	_	pF	1 = 1.0WII IZ	
Total Gate Charge	$Q_g$		622.4	_		\\ 4.5\\\\ 10\\	
Gate-Source Charge	$Q_{gs}$		100.3	_	рC	$V_{GS} = -4.5V, V_{DS} = -10V,$ $I_{D} = -250\text{mA}$	
Gate-Drain Charge	$Q_{gd}$		132.2	_		ID = -230IIIA	
Turn-On Delay Time	t <sub>d(on)</sub>		5.1	_		\\	
Turn-On Rise Time	t <sub>r</sub>		8.1	_	ns	$V_{DD} = -10V, V_{GS} = -4.5V,$ $R_L = 47\Omega, R_G = 10\Omega,$	
Turn-Off Delay Time	t <sub>d(off)</sub>		28.4	_	115	$R_L = 4752, R_G = 1052,$ $I_D = -200 \text{mA}$	
Turn-Off Fall Time	t <sub>f</sub>	_	20.7	_		10 = -200111A	

Notes: 4. Short duration pulse test used to minimize self-heating effect.



## N-CHANNEL - Q<sub>1</sub>





# N-CHANNEL - Q<sub>1</sub> (continued)

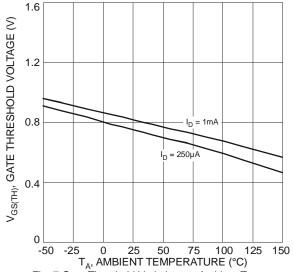
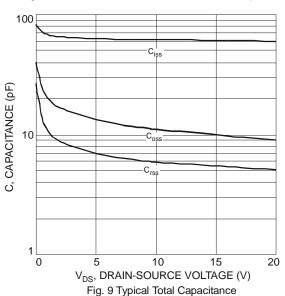
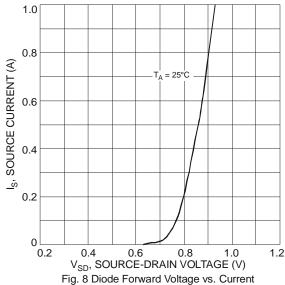


Fig. 7 Gate Threshold Variation vs. Ambient Temperature





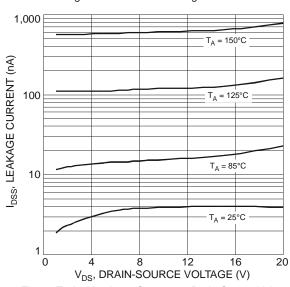


Fig. 10 Typical Leakage Current vs. Drain-Source Voltage

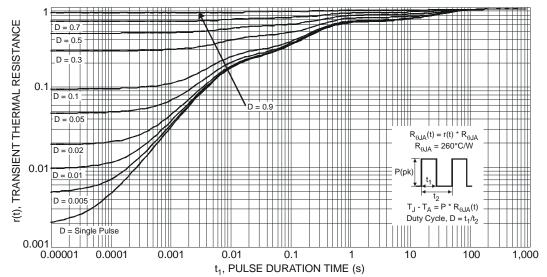
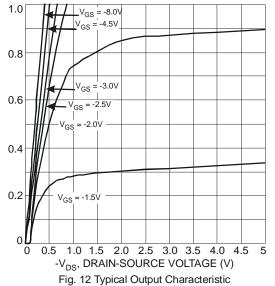


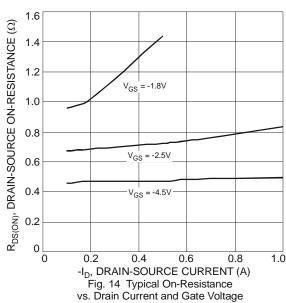
Fig. 11 Transient Thermal Response

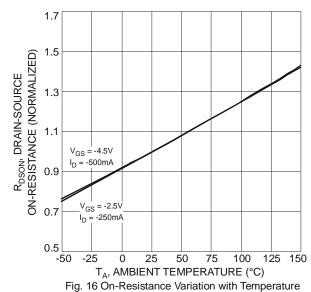
3.0



## P-CHANNEL - Q<sub>2</sub>







(E) LNBUNCORRE O.6

O.2

T<sub>A</sub> = 150°C

T<sub>A</sub> = 25°C

T<sub>A</sub> = 25°C

T<sub>A</sub> = 25°C

T<sub>A</sub> = 55°C

O.5

-V<sub>GS</sub>, GATE-SOURCE VOLTAGE (V)

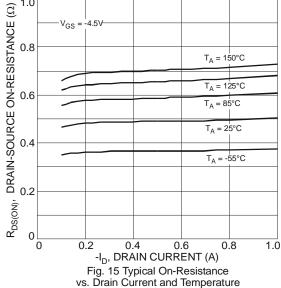
Fig. 13 Typical Transfer Characteristic

(C) T<sub>A</sub> = 150°C

1.0

0.8

 $V_{DS} = -5V$ 



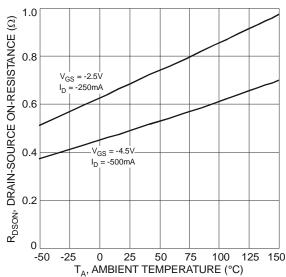
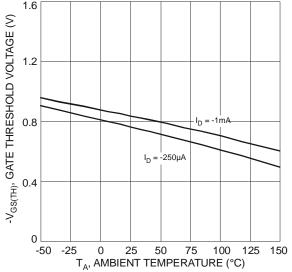
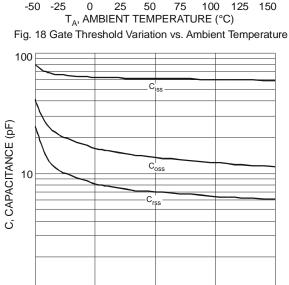


Fig. 17 On-Resistance Variation with Temperature



## P-CHANNEL - Q<sub>2</sub> (continued)

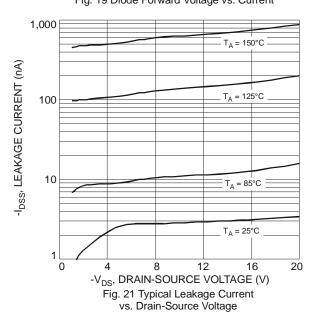


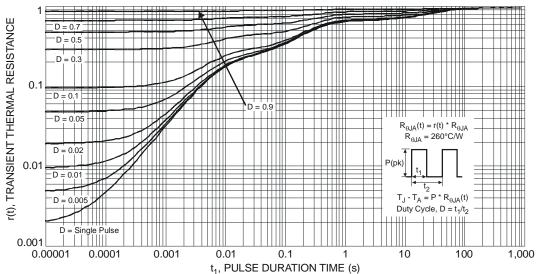


5 10 15 -V<sub>DS</sub>, DRAIN-SOURCE VOLTAGE (V)

Fig. 20 Typical Total Capacitance

1.0 0.8 -I<sub>S</sub>, SOURCE CURRENT (A) .T<sub>A</sub> = 25°C 0.6 0.4 0.2 0 0.2 0.4 0.6 8.0 1.0  $-V_{SD}$ , SOURCE-DRAIN VOLTAGE (V) Fig. 19 Diode Forward Voltage vs. Current





20

Fig. 22 Transient Thermal Response

0

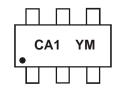


# **Ordering Information** (Note 5)

Part Number	Case	Packaging
DMG1016V-7	SOT-563	3000/Tape & Reel

Notes: 5. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

# **Marking Information**



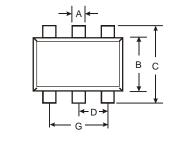
CA1 = Product Type Marking Code YM = Date Code Marking

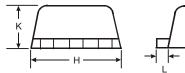
Y = Year (ex: W = 2009) M = Month (ex: 9 = September)

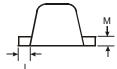
Date Code Key

Year	2009	9	2010		2011	20	12	2013		2014	1	2015
Code	W		Х		Υ	2	7	Α		В		С
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

# **Package Outline Dimensions**

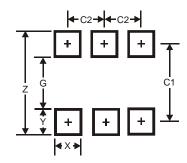






	SOT-563							
Dim	Min	Max	Тур					
Α	0.15	0.30	0.20					
В	1.10	1.25	1.20					
С	1.55	1.70	1.60					
D	-	-	0.50					
G	0.90	1.10	1.00					
Н	1.50	1.70	1.60					
K	0.55	0.60	0.60					
L	0.10	0.30	0.20					
М	0.10	0.18	0.11					
All	All Dimensions in mm							

# **Suggested Pad Layout**



Dimensions	Value (in mm)
Z	2.2
G	1.2
Х	0.375
Y	0.5
C1	1.7
C2	0.5



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